



Material Content Data Sheet



Sales Product Name	TLE4253GS			Issued		28. October 2019		
MA#	MA001674316							
Package	PG-DSO-8-46			Weight*		83.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.205	2.66	2.66	26554	26554
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		436	
	non noble metal	iron	7439-89-6	0.723	0.87		8712	
	non noble metal	copper	7440-50-8	29.372	35.38	36.30	353763	363020
wire	non noble metal	copper	7440-50-8	0.070	0.08	0.08	843	843
encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1165	
	plastics	epoxy resin	-	4.450	5.36		53593	
	inorganic material	silicondioxide	60676-86-0	43.819	52.78	58.26	527776	582534
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9802	9802
plating	noble metal	silver	7440-22-4	0.144	0.17	0.17	1736	1736
glue	plastics	epoxy resin	-	0.322	0.39		3878	
	noble metal	silver	7440-22-4	0.966	1.16	1.55	11633	15511
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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